

General Description

The MAX202E-MAX213E, MAX232E/MAX241E line drivers/receivers are designed for RS-232 and V.28 communications in harsh environments. Each transmitter output and receiver input is protected against ±15kV electrostatic discharge (ESD) shocks, without latchup. The various combinations of features are outlined in the Selector Guide. The drivers and receivers for all ten devices meet all EIA/TIA-232E and CCITT V.28 specifications at data rates up to 120kbps, when loaded in accordance with the EIA/TIA-232E specification.

The MAX211E/MAX213E/MAX241E are available in 28pin SO packages, as well as a 28-pin SSOP that uses 60% less board space. The MAX202E/MAX232E come in 16-pin TSSOP, narrow SO, wide SO, and DIP packages. The MAX203E comes in a 20-pin DIP/SO package, and needs no external charge-pump capacitors. The MAX205E comes in a 24-pin wide DIP package, and also eliminates external charge-pump capacitors. The MAX206E/MAX207E/MAX208E come in 24-pin SO, SSOP, and narrow DIP packages. The MAX232E/MAX241E operate with four 1µF capacitors, while the MAX202E/MAX206E/MAX207E/MAX208E/ MAX211E/MAX213E operate with four 0.1µF capacitors, further reducing cost and board space.

Applications

Notebook, Subnotebook, and Palmtop Computers Battery-Powered Equipment Hand-Held Equipment

Next-Generation Device Features

- ♦ For Low-Voltage Applications MAX3222E/MAX3232E/MAX3237E/MAX3241E/ MAX3246E: ±15kV ESD-Protected Down to 10nA, +3.0V to +5.5V, Up to 1Mbps, True RS-232 Transceivers (MAX3246E Available in a UCSP™ Package)
- **♦** For Low-Power Applications MAX3221/MAX3223/MAX3243: 1µA Supply Current, True +3V to +5.5V RS-232 Transceivers with Auto-Shutdown™
- **♦** For Space-Constrained Applications MAX3233E/MAX3235E: ±15kV ESD-Protected, 1μA, 250kbps, +3.0V/+5.5V, Dual RS-232 **Transceivers with Internal Capacitors**
- **♦** For Low-Voltage or Data Cable Applications MAX3380E/MAX3381E: +2.35V to +5.5V, 1µA, 2Tx/2Rx RS-232 Transceivers with ±15kV ESD-Protected I/O and Logic Pins

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE	
MAX202ECPE	0°C to +70°C	16 Plastic DIP	
MAX202ECSE	0°C to +70°C	16 Narrow SO	

Ordering Information continued at end of data sheet.

Pin Configurations and Typical Operating Circuits appear at end of data sheet.

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Selector Guide

PART	NO. OF RS-232 DRIVERS	NO. OF RS-232 RECEIVERS	RECEIVERS ACTIVE IN SHUTDOWN	NO. OF EXTERNAL CAPACITORS (μF)	LOW-POWER SHUTDOWN	TTL TRI- STATE
MAX202E	2	2	0	4 (0.1)	No	No
MAX203E	2	2	0	None	No	No
MAX205E	5	5	0	None	Yes	Yes
MAX206E	4	3	0	4 (0.1)	Yes	Yes
MAX207E	5	3	0	4 (0.1)	No	No
MAX208E	4	4	0	4 (0.1)	No	No
MAX211E	4	5	0	4 (0.1)	Yes	Yes
MAX213E	4	5	2	4 (0.1)	Yes	Yes
MAX232E	2	2	0	4 (1)	No	No
MAX241E	4	5	0	4 (1)	Yes	Yes

MIXIM

Maxim Integrated Products 1

ABSOLUTE MAXIMUM RATINGS

Vcc	0.3V to +6V
V+	(Vcc - 0.3V) to +14V
V	14V to +0.3V
Input Voltages	
T_IN	
R_IN	±30V
Output Voltages	
T_OUT	
R_OUT	
Short-Circuit Duration, T_OUT	
Continuous Power Dissipation ($T_A = +$,
16-Pin Plastic DIP (derate 10.53mW/°	
16-Pin Narrow SO (derate 8.70mW/°C	,
16-Pin Wide SO (derate 9.52mW/°C	,
16-Pin TSSOP (derate 9.4mW/°C abo	ove +70°C)755mW

20-Pin Plastic DIP (derate 11.11mW/°C above +70°C)889mW 20-Pin SO (derate 10.00mW/°C above +70°C)800mW
24-Pin Narrow Plastic DIP
(derate 13.33mW/°C above +70°C)1.07W 24-Pin Wide Plastic DIP
=
(derate 14.29mW/°C above +70°C)1.14W
24-Pin SO (derate 11.76mW/°C above +70°C)941mW
24-Pin SSOP (derate 8.00mW/°C above +70°C)640mW
28-Pin SO (derate 12.50mW/°C above +70°C)1W
28-Pin SSOP (derate 9.52mW/°C above +70°C)762mW
Operating Temperature Ranges
MAX2EC0°C to +70°C
MAX2EE40°C to +85°C
Storage Temperature Range65°C to +165°C
Lead Temperature (soldering, 10s)+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{CC} = +5V \pm 10\% \text{ for MAX202E/206E/208E/211E/213E/232E/241E; } V_{CC} = +5V \pm 5\% \text{ for MAX203E/205E/207E; } C1-C4 = 0.1 \mu F \text{ for MAX202E/206E/207E/208E/211E/213E; } C1-C4 = 1 \mu F \text{ for MAX232E/241E; } T_{A} = T_{MIN} \text{ to } T_{MAX}; \text{ unless otherwise noted. Typical values are at } T_{A} = +25^{\circ}C.)$

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS		
DC CHARACTERISTICS									
			MAX202E/203E		8	15	mA		
			MAX205E-208E		11	20			
V _{CC} Supply Current	Icc	No load, $T_A = +25^{\circ}C$	MAX211E/213E		14	20			
			MAX232E		5	10	1		
			MAX241E		7	15			
			MAX205E/206E		1	10			
Shutdown Supply Current		T _A = +25°C, Figure 1	MAX211E/241E		1	10	μΑ		
			MAX213E		15	50			
LOGIC									
Input Pullup Current		T_IN = 0V (MAX205E-208E/2	11E/213E/241E)		15	200	μΑ		
Input Leakage Current		$T_IN = 0V \text{ to } V_{CC} \text{ (MAX202B)}$	E/203E/232E)			±10	μΑ		
Input Threshold Low	VIL	T_IN; EN, SHDN (MAX213E; EN, SHDN (MAX205E–208E				0.8	V		
		T_IN		2.0					
Input Threshold High	VIH	EN, SHDN (MAX213E) or EN (MAX205E-208E/211E/241E		2.4			V		
Output-Voltage Low	VoL	R_OUT; I _{OUT} = 3.2mA (MAX202E/203E/232E) or I _{OUT} = 1.6mA (MAX205E/208E/211E/213E/241E)				0.4	V		
Output-Voltage High	VoH	R_OUT; $I_{OUT} = -1.0 \text{mA}$ 3.5 $V_{CC} - 0.4$			V				
Output Leakage Current		$\overline{\text{EN}} = \text{V}_{\text{CC}}, \text{ EN} = \text{OV}, \text{ OV} \leq \text{R}_{\text{C}}$ MAX205E-208E/211E/213E/			±0.05	±10	μА		

ELECTRICAL CHARACTERISTICS (continued)

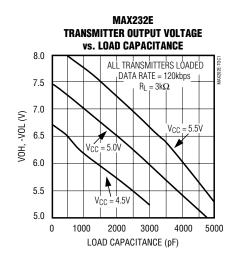
(VCC = +5V \pm 10% for MAX202E/206E/208E/211E/213E/232E/241E; VCC = +5V \pm 5% for MAX203E/205E/207E; C1–C4 = 0.1µF for MAX202E/206E/207E/208E/211E/213E; C1–C4 = 1µF for MAX232E/241E; TA = TMIN to TMAX; unless otherwise noted. Typical values are at TA = +25°C.)

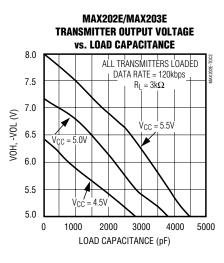
PARAMETER	SYMBOL	C	CONDITIONS	MIN	TYP	MAX	UNITS
EIA/TIA-232E RECEIVER INPU	гѕ						
Input Voltage Range				-30		30	V
		T 0500	All parts, normal operation	0.8	1.2		
Input Threshold Low		$T_A = +25^{\circ}C$, $V_{CC} = 5V$	MAX213E, SHDN = 0V, EN = V _{CC}	0.6	1.5		V
			All parts, normal operation		1.7	2.4	
Input Threshold High		$T_A = +25^{\circ}C,$ $V_{CC} = 5V$	MAX213E (R4, R5), SHDN = 0V, EN = V _{CC}		1.5	2.4	V
Input Hysteresis		V _{CC} = 5V, no hys	teresis in shutdown	0.2	0.5	1.0	V
Input Resistance		$T_A = +25$ °C, V_{CC}	= 5V	3	5	7	kΩ
EIA/TIA-232E TRANSMITTER	OUTPUTS	1					1
Output Voltage Swing		All drivers loaded	I with 3kΩ to ground (Note 1)	±5	±9		V
Output Resistance		V _C C = V+ = V- =	$0V, V_{OUT} = \pm 2V$	300			Ω
Output Short-Circuit Current					±10	±60	mA
TIMING CHARACTERISTICS							
Maximum Data Rate		$R_L = 3k\Omega$ to $7k\Omega$, one transmitter sv	C _L = 50pF to 1000pF, witching	120			kbps
			All parts, normal operation		0.5	10	
Receiver Propagation Delay	tPLHR, tPHLR	C _L = 150pF	MAX213E (R4, R5), SHDN = 0V, EN = V _{CC}		4	40	μs
Receiver Output Enable Time		MAX205E/206E/2 operation, Figure	211E/213E/241E normal 2		600		ns
Receiver Output Disable Time		MAX205E/206E/2 operation, Figure	211E/213E/241E normal 2		200		ns
Transmitter Propagation Delay	tpLHT,	$R_L = 3k\Omega$, $C_L = 2$	$R_L = 3k\Omega$, $C_L = 2500pF$, all transmitters loaded		2		μs
Transition-Region Slew Rate		TA = +25°C, V _{CC} = 5V, R _L = $3k\Omega$ to $7k\Omega$, C _L = $50pF$ to $1000pF$, measured from -3V to +3V or +3V to -3V, Figure 3		3	6	30	V/µs
ESD PERFORMANCE: TRANS	MITTER OL	JTPUTS, RECEIVE	R INPUTS				
		Human Body Mod	del		±15		
ESD-Protection Voltage		IEC1000-4-2, Cor	<u> </u>		±8		kV
		IEC1000-4-2, Air-	Gap Discharge		±15		

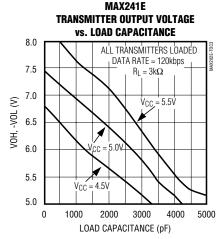
Note 1: MAX211EE_ _ tested with $V_{CC} = +5V \pm 5\%$.

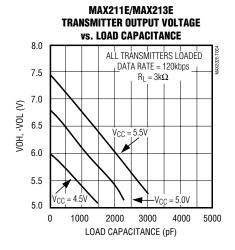
Typical Operating Characteristics

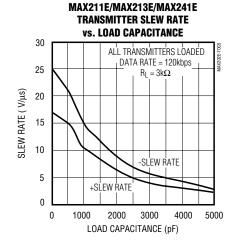
(Typical Operating Circuits, V_{CC} = +5V, T_A = +25°C, unless otherwise noted.)





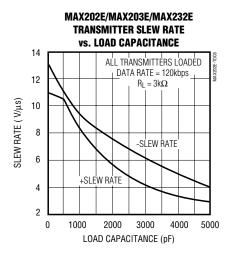


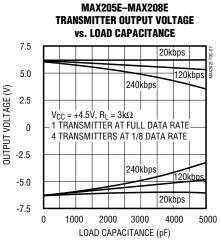


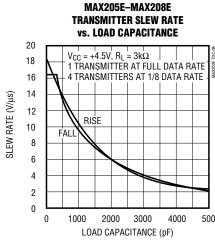


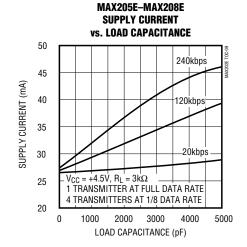
Typical Operating Characteristics (continued)

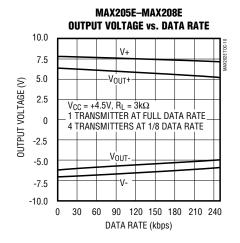
(Typical Operating Circuits, V_{CC} = +5V, T_A = +25°C, unless otherwise noted.)











Pin Descriptions

MAX202E/MAX232E

PI	PIN		FUNCTION
DIP/SO/TSSOP	LCC	NAME	FUNCTION
1, 3	2, 4	C1+, C1-	Terminals for Positive Charge-Pump Capacitor
2	3	V+	+2V _{CC} Voltage Generated by the Charge Pump
4, 5	5, 7	C2+, C2-	Terminals for Negative Charge-Pump Capacitor
6	8	V-	-2V _{CC} Voltage Generated by the Charge Pump
7, 14	9, 18	T_OUT	RS-232 Driver Outputs
8, 13	10, 17	R_IN	RS-232 Receiver Inputs
9, 12	12, 15	R_OUT	RS-232 Receiver Outputs
10, 11	13, 14	T_IN	RS-232 Driver Inputs
15	19	GND	Ground
16	20	Vcc	+4.5V to +5.5V Supply-Voltage Input
	1, 6, 11, 16	N.C.	No Connection—Not Internally Connected

MAX203E

P	PIN		FUNCTION	
DIP	so	NAME	TONOTION	
1, 2	1, 2	T_IN	RS-232 Driver Inputs	
3, 20	3, 20	R_OUT	RS-232 Receiver Outputs	
4,19	4, 19	R_IN	RS-232 Receiver Inputs	
5,18	5, 18	T_OUT	RS-232 Transmitter Outputs	
6, 9	6, 9	GND	Ground	
7	7	Vcc	+4.5V to +5.5V Supply-Voltage Input	
8	13	C1+	Make no connection to this pin.	
10, 16	11, 16	C2-	Connect pins together.	
12, 17	10, 17	V-	-2V _{CC} Voltage Generated by the Charge Pump. Connect pins together.	
13	14	C1-	Make no connection to this pin.	
14	8	V+	+2VCC Voltage Generated by the Charge Pump	
11, 15	12, 15	C2+	Connect pins together.	

MAX205E

PIN	NAME	FUNCTION	
1–4, 19	T_OUT	RS-232 Driver Outputs	
5, 10, 13, 18, 24	R_IN	RS-232 Receiver Inputs	
6, 9, 14, 17, 23	R_OUT	TTL/CMOS Receiver Outputs. All receivers are inactive in shutdown.	
7, 8, 15, 16, 22	T_IN	TTL/CMOS Driver Inputs. Internal pullups to V _{CC} .	
11	GND	Ground	
12	V _{CC}	+4.75V to +5.25V Supply Voltage	
20	ĒN	Receiver Enable—Active Low	
21	SHDN	Shutdown Control—Active High	

__Pin Descriptions (continued)

MAX206E

PIN	NAME	FUNCTION
1, 2, 3, 24	T_OUT	RS-232 Driver Outputs
4, 16, 23	R_IN	RS-232 Receiver Inputs
5, 17, 22	R_OUT	TTL/CMOS Receiver Outputs. All receivers are inactive in shutdown.
6, 7, 18, 19	T_IN	TTL/CMOS Driver Inputs. Internal pullups to V _{CC} .
8	GND	Ground
9	Vcc	+4.5V to +5.5V Supply Voltage
10, 12	C1+, C1-	Terminals for Positive Charge-Pump Capacitor
11	V+	+2V _{CC} Generated by the Charge Pump
13, 14	C2+, C2-	Terminals for Negative Charge-Pump Capacitor
15	V-	-2V _{CC} Generated by the Charge Pump
20	ĒN	Receiver Enable—Active Low
21	SHDN	Shutdown Control—Active High

MAX207E

PIN	NAME	FUNCTION
1, 2, 3, 20, 24	T_OUT	RS-232 Driver Outputs
4, 16, 23	R_IN	RS-232 Receiver Inputs
5, 17, 22	R_OUT	TTL/CMOS Receiver Outputs. All receivers are inactive in shutdown.
6, 7, 18, 19, 21	T_IN	TTL/CMOS Driver Inputs. Internal pullups to VCC.
8	GND	Ground
9	Vcc	+4.75V to +5.25V Supply Voltage
10, 12	C1+, C1-	Terminals for Positive Charge-Pump Capacitor
11	V+	+2Vcc Generated by the Charge Pump
13, 14	13, 14 C2+, C2- Terminals for Negative Charge-Pump Capacitor	
15	V-	-2VCC Generated by the Charge Pump

MAX208E

PIN	NAME	FUNCTION	
1, 2, 20, 24	T_OUT	RS-232 Driver Outputs	
3, 7, 16, 23	R_IN	RS-232 Receiver Inputs	
4, 6, 17, 22	R_OUT	TTL/CMOS Receiver Outputs. All receivers are inactive in shutdown.	
5, 18, 19, 21	T_IN	TTL/CMOS Driver Inputs. Internal pullups to V _{CC} .	
8	GND	Ground	
9	V _{CC}	+4.5V to +5.5V Supply Voltage	
10, 12	C1+, C1-	Terminals for Positive Charge-Pump Capacitor	
11	V+	+2V _{CC} Generated by the Charge Pump	
13, 14	C2+, C2-	Terminals for Negative Charge-Pump Capacitor	
15	V-	-2V _{CC} Generated by the Charge Pump	

Pin Descriptions (continued)

MAX211E/MAX213E/MAX241E

PIN	NAME	FUNCTION	
1, 2, 3, 28	T_OUT	RS-232 Driver Outputs	
4, 9, 18, 23, 27	R_IN	RS-232 Receiver Inputs	
5, 8, 19, 22, 26	R_OUT	TTL/CMOS Receiver Outputs. For the MAX213E, receivers R4 and R5 are active in shutdown mode when EN = 1. For the MAX211E and MAX241E, all receivers are inactive in shutdown.	
6, 7, 20, 21	T_IN	TTL/CMOS Driver Inputs. Only the MAX211E, MAX213E, and MAX241E have internal pullups to VCC.	
10	GND	Ground	
11	Vcc	+4.5V to +5.5V Supply Voltage	
12, 14 C1+, C1- Terminals for Positive Charge-Pump Capacitor 13 V+ +2V _{CC} Voltage Generated by the Charge Pump 15, 16 C2+, C2- Terminals for Negative Charge-Pump Capacitor 17 V2V _{CC} Voltage Generated by the Charge Pump		Terminals for Positive Charge-Pump Capacitor	
		+2V _{CC} Voltage Generated by the Charge Pump	
		Terminals for Negative Charge-Pump Capacitor	
		-2V _{CC} Voltage Generated by the Charge Pump	
24	ĒN	Receiver Enable—Active Low (MAX211E, MAX241E)	
24	EN	Receiver Enable—Active High (MAX213E)	
25	SHDN	Shutdown Control—Active High (MAX211E, MAX241E)	
20	SHDN	Shutdown Control—Active Low (MAX213E)	

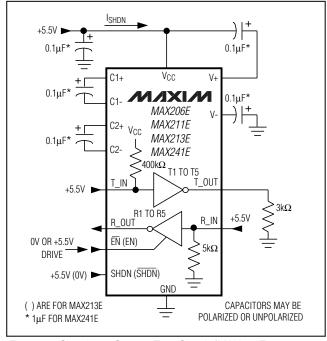


Figure 1. Shutdown-Current Test Circuit (MAX206E, MAX211E/MAX213E/MAX241E)

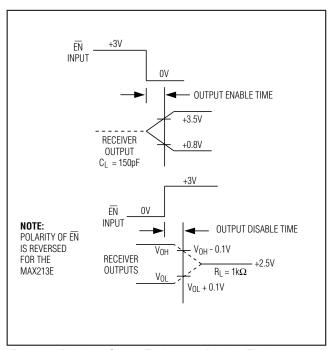


Figure 2. Receiver Output Enable and Disable Timing (MAX205E/MAX206E/MAX211E/MAX213E/MAX241E)

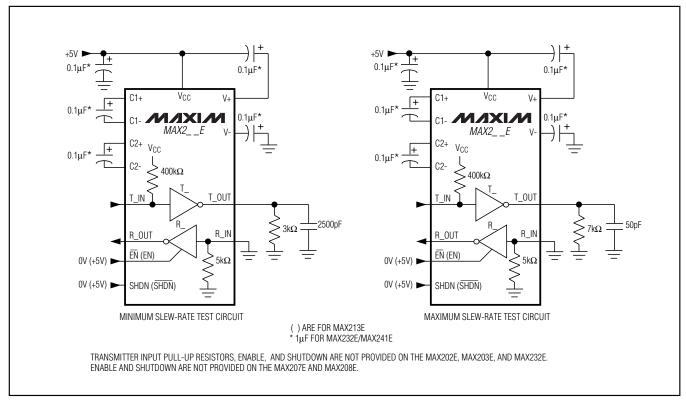


Figure 3. Transition Slew-Rate Circuit

Detailed Description

The MAX202E–MAX213E, MAX232E/MAX241E consist of three sections: charge-pump voltage converters, drivers (transmitters), and receivers. These E versions provide extra protection against ESD. They survive ±15kV discharges to the RS-232 inputs and outputs, tested using the Human Body Model. When tested according to IEC1000-4-2, they survive ±8kV contact-discharges and ±15kV air-gap discharges. The rugged E versions are intended for use in harsh environments or applications where the RS-232 connection is frequently changed (such as notebook computers). The standard (non-"E") MAX202, MAX203, MAX205–MAX208, MAX211, MAX213, MAX232, and MAX241 are recommended for applications where cost is critical.

+5V to ±10V Dual Charge-Pump Voltage Converter

The +5V to $\pm 10V$ conversion is performed by dual charge-pump voltage converters (Figure 4). The first charge-pump converter uses capacitor C1 to double the +5V into +10V, storing the +10V on the output filter capacitor, C3. The second uses C2 to invert the +10V

into -10V, storing the -10V on the V- output filter capacitor, C4.

In shutdown mode, V+ is internally connected to VCC by a 1k Ω pull-down resistor, and V- is internally connected to ground by a 1k Ω pull up resistor.

RS-232 Drivers

With V_{CC} = 5V, the typical driver output voltage swing is $\pm 8V$ when loaded with a nominal $5k\Omega$ RS-232 receiver. The output swing is guaranteed to meet EIA/TIA-232E and V.28 specifications that call for $\pm 5V$ minimum output levels under worst-case conditions. These include a $3k\Omega$ load, minimum V_{CC}, and maximum operating temperature. The open-circuit output voltage swings from (V+ - 0.6V) to V-.

Input thresholds are CMOS/TTL compatible. The unused drivers' inputs on the MAX205E–MAX208E, MAX211E, MAX213E, and MAX241E can be left unconnected because 400k Ω pull up resistors to VCC are included on-chip. Since all drivers invert, the pull up resistors force the unused drivers' outputs low. The MAX202E, MAX203E, and MAX232E do not have pull up resistors on the transmitter inputs.

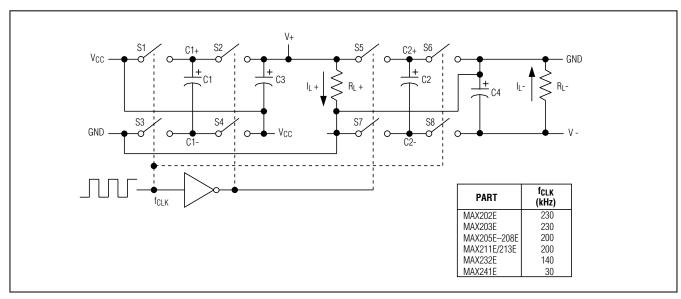


Figure 4. Charge-Pump Diagram

When in low-power shutdown mode, the MAX205E/MAX206E/MAX211E/MAX213E/MAX241E driver outputs are turned off and draw only leakage currents—even if they are back-driven with voltages between 0V and 12V. Below -0.5V in shutdown, the transmitter output is diode-clamped to ground with a $1 \text{k}\Omega$ series impedance.

RS-232 Receivers

The receivers convert the RS-232 signals to CMOS-logic output levels. The guaranteed 0.8V and 2.4V receiver input thresholds are significantly tighter than the ±3V thresholds required by the EIA/TIA-232E specification. This allows the receiver inputs to respond to TTL/CMOS-logic levels, as well as RS-232 levels.

The guaranteed 0.8V input low threshold ensures that receivers shorted to ground have a logic 1 output. The $5k\Omega$ input resistance to ground ensures that a receiver with its input left open will also have a logic 1 output.

Receiver inputs have approximately 0.5V hysteresis. This provides clean output transitions, even with slow rise/fall-time signals with moderate amounts of noise and ringing.

In shutdown, the MAX213E's R4 and R5 receivers have no hysteresis.

Shutdown and Enable Control (MAX205E/MAX206E/MAX211E/ MAX213E/MAX241E)

In shutdown mode, the charge pumps are turned off, V+ is pulled down to V_{CC}, V- is pulled to ground, and the transmitter outputs are disabled. This reduces supply current typically to 1μ A (15μ A for the MAX213E). The time required to exit shutdown is under 1ms, as shown in Figure 5.

Receivers

All MAX213E receivers, except R4 and R5, are put into a high-impedance state in shutdown mode (see Tables 1a and 1b). The MAX213E's R4 and R5 receivers still function in shutdown mode. These two awake-in-shutdown receivers can monitor external activity while maintaining minimal power consumption.

The enable control is used to put the receiver outputs into a high-impedance state, to allow wire-OR connection of two EIA/TIA-232E ports (or ports of different types) at the UART. It has no effect on the RS-232 drivers or the charge pumps.

Note: The enable control pin is active low for the MAX211E/MAX241E (EN), but is active high for the MAX213E (EN). The shutdown control pin is active high for the MAX205E/MAX206E/MAX211E/MAX241E (SHDN), but is active low for the MAX213E (SHDN).

The MAX213E's receiver propagation delay is typically $0.5\mu s$ in normal operation. In shutdown mode, propagation delay increases to $4\mu s$ for both rising and falling transitions. The MAX213E's receiver inputs have approximately 0.5V hysteresis, except in shutdown, when receivers R4 and R5 have no hysteresis.

When entering shutdown with receivers active, R4 and R5 are not valid until 80µs after SHDN is driven low. When coming out of shutdown, all receiver outputs are invalid until the charge pumps reach nominal voltage levels (less than 2ms when using 0.1µF capacitors).

±15kV ESD Protection

As with all Maxim devices, ESD-protection structures are incorporated on all pins to protect against electrostatic discharges encountered during handling and assembly. The driver outputs and receiver inputs have extra protection against static electricity. Maxim's engineers developed state-of-the-art structures to protect these pins against ESD of ±15kV without damage. The ESD structures withstand high ESD in all states: normal operation, shutdown, and powered down. After an ESD event, Maxim's E versions keep working without latchup, whereas competing RS-232 products can latch and must be powered down to remove latchup.

ESD protection can be tested in various ways; the transmitter outputs and receiver inputs of this product family are characterized for protection to the following limits:

- 1) ±15kV using the Human Body Model
- 2) ±8kV using the contact-discharge method specified in IEC1000-4-2
- 3) ±15kV using IEC1000-4-2's air-gap method.

ESD Test Conditions

ESD performance depends on a variety of conditions. Contact Maxim for a reliability report that documents test set-up, test methodology, and test results.

Human Body Model

Figure 6a shows the Human Body Model, and Figure 6b shows the current waveform it generates when discharged into a low impedance. This model consists of a 100pF capacitor charged to the ESD voltage of interest, which is then discharged into the test device through a 1.5k Ω resistor.

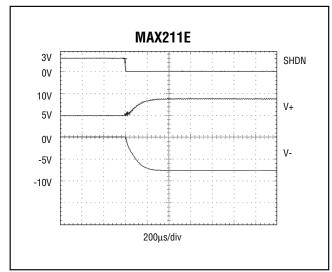


Figure 5. MAX211E V+ and V- when Exiting Shutdown (0.1μF capacitors)

Table 1a. MAX205E/MAX206E/MAX211E/MAX241E Control Pin Configurations

SHDN	EN	OPERATION STATUS	Тх	Rx
0	0	Normal Operation	All Active	All Active
0	1	Normal Operation	All Active	All High-Z
1	Х	Shutdown	All High-Z	All High-Z

X = Don't care.

Table 1b. MAX213E Control Pin Configurations

SHDN	EN	OPERATION STATUS	Tx 1–4	Rx	
SHUN			1 X 1—4	1–3	4, 5
0	0	Shutdown	All High-Z	High-Z	High-Z
0	1	Shutdown	All High-Z	High-Z	Active*
1	0	Normal Operation	All Active	High-Z	High-Z
1	1	Normal Operation	All Active	Active	Active

^{*}Active = active with reduced performance

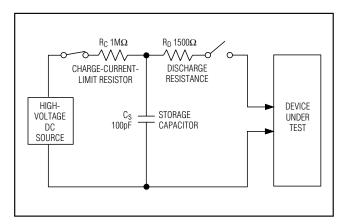


Figure 6a. Human Body ESD Test Model

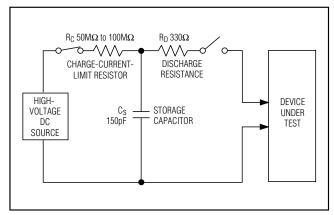


Figure 7a. IEC1000-4-2 ESD Test Model

IEC1000-4-2

The IEC1000-4-2 standard covers ESD testing and performance of finished equipment; it does not specifically refer to integrated circuits. The MAX202E/MAX203E–MAX213E, MAX232E/MAX241E help you design equipment that meets level 4 (the highest level) of IEC1000-4-2, without the need for additional ESD-protection components.

The major difference between tests done using the Human Body Model and IEC1000-4-2 is higher peak current in IEC1000-4-2, because series resistance is lower in the IEC1000-4-2 model. Hence, the ESD withstand voltage measured to IEC1000-4-2 is generally lower than that measured using the Human Body Model. Figure 7b shows the current waveform for the 8kV IEC1000-4-2 level-four ESD contact-discharge test.

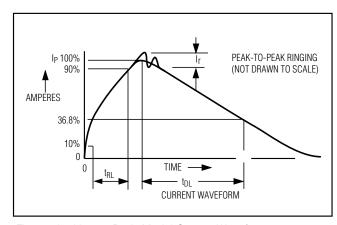


Figure 6b. Human Body Model Current Waveform

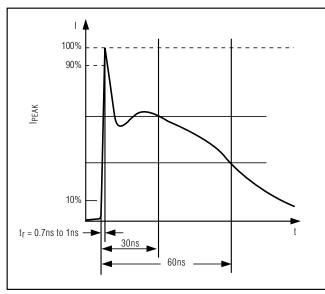


Figure 7b. IEC1000-4-2 ESD Generator Current Waveform

The air-gap test involves approaching the device with a charged probe. The contact-discharge method connects the probe to the device before the probe is energized.

Machine Model

The Machine Model for ESD tests all pins using a 200pF storage capacitor and zero discharge resistance. Its objective is to emulate the stress caused by contact that occurs with handling and assembly during manufacturing. Of course, all pins require this protection during manufacturing, not just RS-232 inputs and outputs. Therefore, after PC board assembly, the Machine Model is less relevant to I/O ports.

Applications Information

Capacitor Selection

The capacitor type used for C1-C4 is not critical for proper operation. The MAX202E, MAX206-MAX208E, MAX211E, and MAX213E require 0.1µF capacitors. and the MAX232E and MAX241E require 1µF capacitors, although in all cases capacitors up to 10µF can be used without harm. Ceramic, aluminumelectrolytic, or tantalum capacitors are suggested for the 1µF capacitors, and ceramic dielectrics are suggested for the 0.1µF capacitors. When using the minimum recommended capacitor values, make sure the capacitance value does not degrade excessively as the operating temperature varies. If in doubt, use capacitors with a larger (e.g., 2x) nominal value. The capacitors' effective series resistance (ESR), which usually rises at low temperatures, influences the amount of ripple on V+ and V-.

Use larger capacitors (up to 10μ F) to reduce the output impedance at V+ and V-. This can be useful when "stealing" power from V+ or from V-. The MAX203E and MAX205E have internal charge-pump capacitors.

Bypass VCC to ground with at least $0.1\mu F$. In applications sensitive to power-supply noise generated by the charge pumps, decouple VCC to ground with a capacitor the same size as (or larger than) the charge-pump capacitors (C1–C4).

V+ and V- as Power Supplies

A small amount of power can be drawn from V+ and V-, although this will reduce both driver output swing and noise margins. Increasing the value of the charge-pump capacitors (up to $10\mu F$) helps maintain performance when power is drawn from V+ or V-.

Driving Multiple Receivers

Each transmitter is designed to drive a single receiver. Transmitters can be paralleled to drive multiple receivers.

Driver Outputs when Exiting Shutdown

The driver outputs display no ringing or undesirable transients as they come out of shutdown.

High Data Rates

These transceivers maintain the RS-232 ±5.0V minimum driver output voltages at data rates of over 120kbps. For data rates above 120kbps, refer to the Transmitter Output Voltage vs. Load Capacitance graphs in the *Typical Operating Characteristics*. Communication at these high rates is easier if the capacitive loads on the transmitters are small; i.e., short cables are best.

Table 2. Summary of EIA/TIA-232E, V.28 Specifications

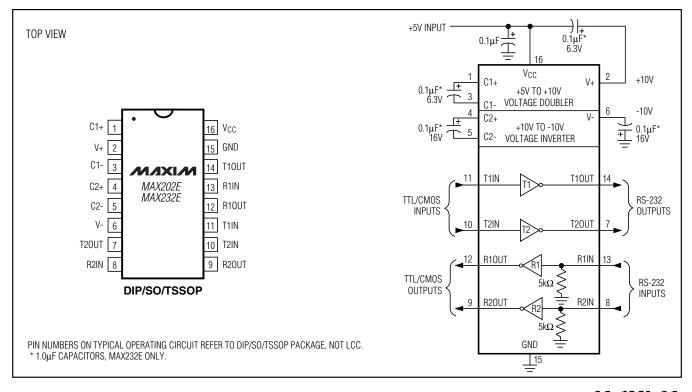
PARAMETER		CONDITIONS	EIA/TIA-232E, V.28 SPECIFICATIONS	
Driver Output Voltage	0 Level	$3k\Omega$ to $7k\Omega$ load	+5V to +15V	
Driver Output Voltage	1 Level	$3k\Omega$ to $7k\Omega$ load	-5V to -15V	
Driver Output Level, Max		No load	±25V	
Data Rate		$3k\Omega \le R_L \le 7k\Omega$, $C_L \le 2500pF$	Up to 20kbps	
Desciver Input Veltage	0 Level		+3V to +15V	
Receiver Input Voltage	1 Level		-3V to -15V	
Receiver Input Level Instantaneous Slew Rate, Max Driver Output Short-Circuit Current, Max			±25V	
		$3k\Omega \le R_L \le 7k\Omega$, $C_L \le 2500pF$	30V/µs	
			100mA	
Transition Pate on Driver (Outout	V.28	1ms or 3% of the period	
Transition Rate on Driver (Juipui	EIA/TIA-232E	4% of the period	
Driver Output Resistance		-2V < V _{OUT} < +2V	300Ω	



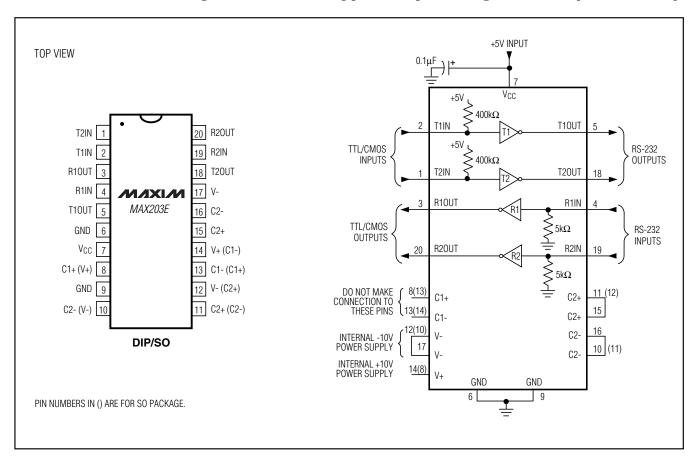
Table 3. DB9 Cable Connections Commonly Used for EIA/TIAE-232E and V.24 Asynchronous Interfaces

PIN	CONNE	CTION
1	Received Line Signal Detector (sometimes called Carrier Detect, DCD)	Handshake from DCE
2	Receive Data (RD)	Data from DCE
3	Transmit Data (TD)	Data from DTE
4	Data Terminal Ready	Handshake from DTE
5	Signal Ground	Reference point for signals
6	Data Set Ready (DSR)	Handshake from DCE
7	Request to Send (RTS)	Handshake from DTE
8	Clear to Send (CTS)	Handshake from DCE
9	Ring Indicator	Handshake from DCE

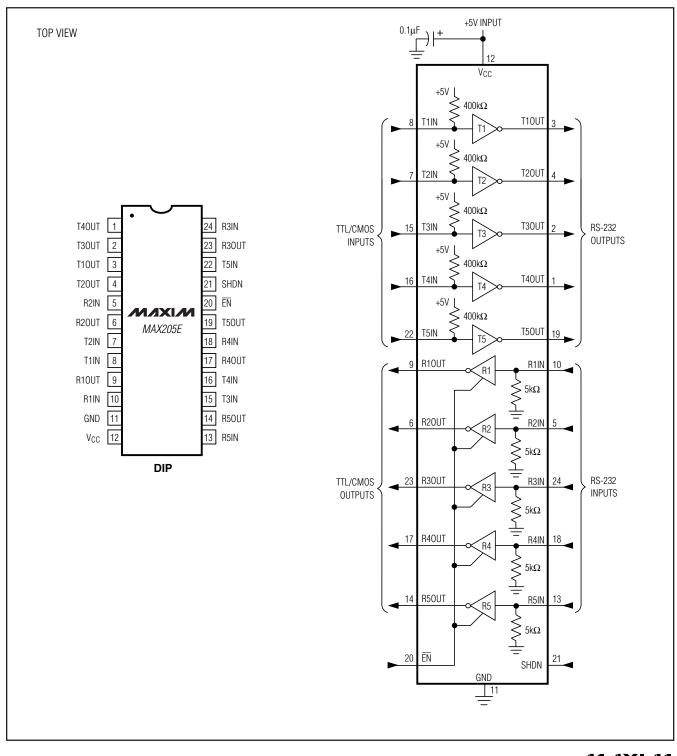
Pin Configurations and Typical Operating Circuits (continued)



Pin Configurations and Typical Operating Circuits (continued)

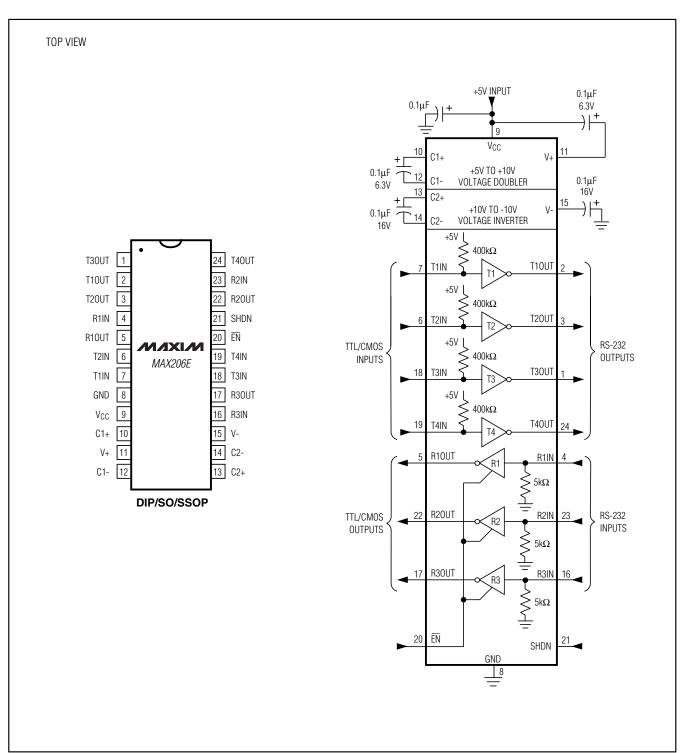


Pin Configurations and Typical Operating Circuits (continued)

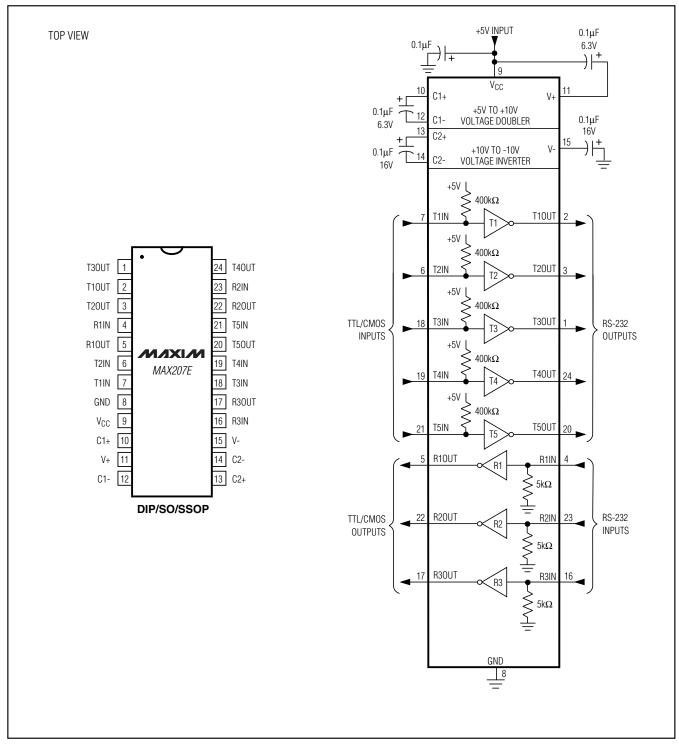


16 ______ /V/XI/VI

Pin Configurations and Typical Operating Circuits (continued)

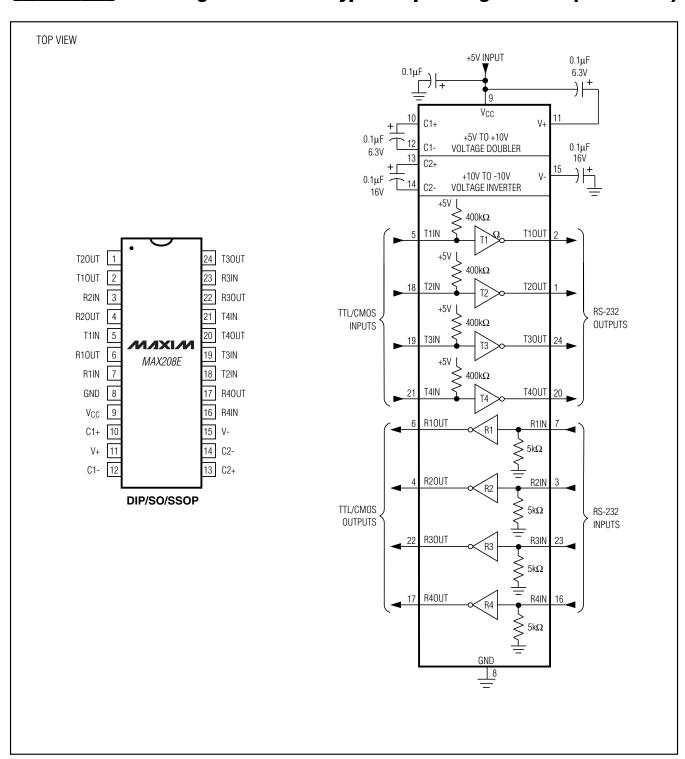


Pin Configurations and Typical Operating Circuits (continued)

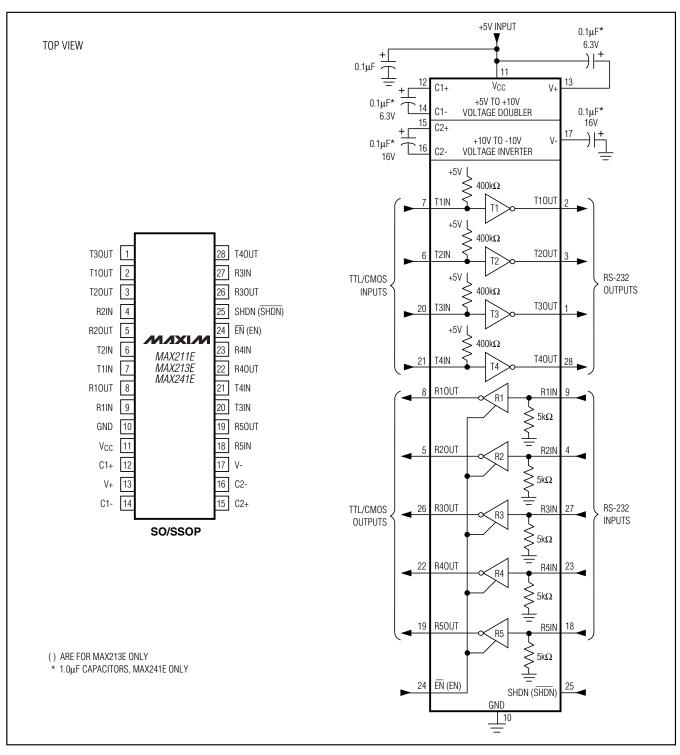


MIXIM

Pin Configurations and Typical Operating Circuits (continued)



Pin Configurations and Typical Operating Circuits (continued)



M/IXI/N

MAX202E-MAX213E, MAX232E/MAX241E

±15kV ESD-Protected, +5V RS-232 Transceivers

Ordering Information (continued)

DADT	TEMP DANCE	DINI DAOKAGE
PART	TEMP RANGE	PIN-PACKAGE
MAX202ECUE	0°C to +70°C	16 TSSOP
MAX202ECWE	0°C to +70°C	16 Wide SO
MAX202EC/D	0°C to +70°C	Dice*
MAX202EEPE	-40°C to +85°C	16 Plastic DIP
MAX202EESE	-40°C to +85°C	16 Narrow SO
MAX202EEUE	-40°C to +85°C	16 TSSOP
MAX202EEWE	-40°C to +85°C	16 Wide SO
MAX203ECPP	0°C to +70°C	20 Plastic DIP
MAX203ECWP	0°C to +70°C	20 SO
MAX203EEPP	-40°C to +85°C	20 Plastic DIP
MAX203EEWP	-40°C to +85°C	20 SO
MAX205ECPG	0°C to +70°C	24 Wide Plastic DIP
MAX205EEPG	-40°C to +85°C	24 Wide Plastic DIP
MAX206ECNG	0°C to +70°C	24 Narrow Plastic DIP
MAX206ECWG	0°C to +70°C	24 SO
MAX206ECAG	0°C to +70°C	24 SSOP
MAX206EENG	-40°C to +85°C	24 Narrow Plastic DIP
MAX206EEWG	-40°C to +85°C	24 SO
MAX206EEAG	-40°C to +85°C	24 SSOP
MAX207ECNG	0°C to +70°C	24 Narrow Plastic DIP
MAX207ECWG	0°C to +70°C	24 SO
MAX207ECAG	0°C to +70°C	24 SSOP
MAX207EENG	-40°C to +85°C	24 Narrow Plastic DIP
MAX207EEWG	-40°C to +85°C	24 SO
MAX207EEAG	-40°C to +85°C	24 SSOP

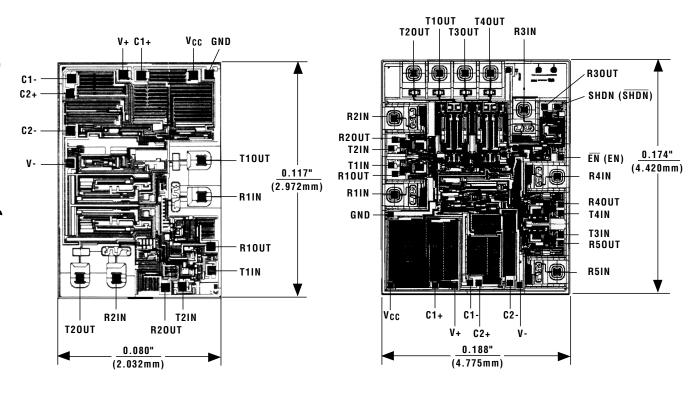
PART	TEMP RANGE	PIN-PACKAGE
MAX208ECNG	0°C to +70°C	24 Narrow Plastic DIP
MAX208ECWG	0°C to +70°C	24 SO
MAX208ECAG	0°C to +70°C	24 SSOP
MAX208EENG	-40°C to +85°C	24 Narrow Plastic DIP
MAX208EEWG	-40°C to +85°C	24 SO
MAX208EEAG	-40°C to +85°C	24 SSOP
MAX211ECWI	0°C to +70°C	28 SO
MAX211ECAI	0°C to +70°C	28 SSOP
MAX211EEWI	-40°C to +85°C	28 SO
MAX211EEAI	-40°C to +85°C	28 SSOP
MAX213ECWI	0°C to +70°C	28 SO
MAX213ECAI	0°C to +70°C	28 SSOP
MAX213EEWI	-40°C to +85°C	28 SO
MAX213EEAI	-40°C to +85°C	28 SSOP
MAX232ECPE	0°C to +70°C	16 Plastic DIP
MAX232ECSE	0°C to +70°C	16 Narrow SO
MAX232ECWE	0°C to +70°C	16 Wide SO
MAX232EC/D	0°C to +70°C	Dice*
MAX232EEPE	-40°C to +85°C	16 Plastic DIP
MAX232EESE	-40°C to +85°C	16 Narrow SO
MAX232EEWE	-40°C to +85°C	16 Wide SO
MAX241ECWI	0°C to +70°C	28 SO
MAX241ECAI	0°C to +70°C	28 SSOP
MAX241EEWI	-40°C to +85°C	28 SO
MAX241EEAI	-40°C to +85°C	28 SSOP

^{*}Dice are specified at $T_A = +25$ °C.

Chip Topographies

MAX202E/MAX232E

MAX211E/MAX213E/MAX241E



() ARE FOR MAX213E ONLY

TRANSISTOR COUNT: 123
SUBSTRATE CONNECTED TO GND

TRANSISTOR COUNT: 542
SUBSTRATE CONNECTED TO GND

Chip Information

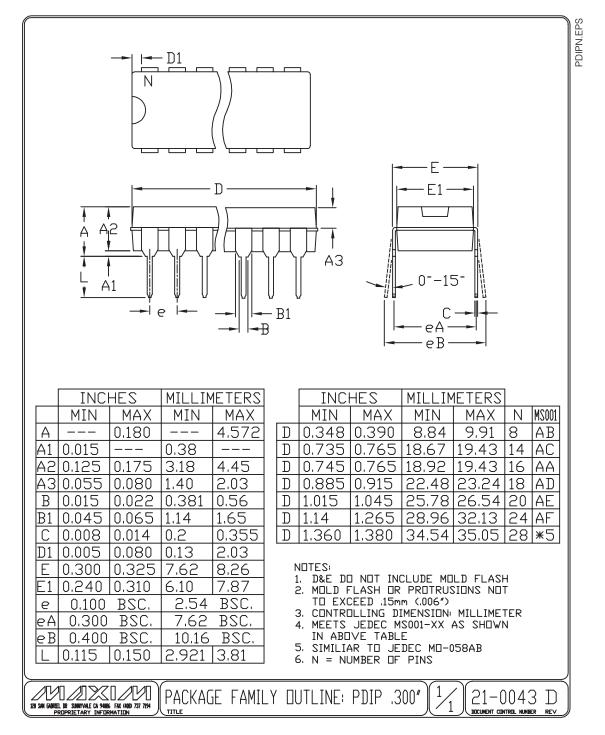
MAX205E/MAX206E/MAX207E/MAX208E

TRANSISTOR COUNT: 328

SUBSTRATE CONNECTED TO GND

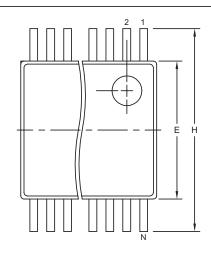
Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to www.maxim-ic.com/packages.)



Package Information (continued)

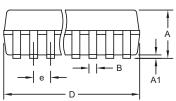
(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to www.maxim-ic.com/packages.)

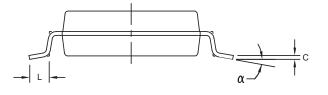


	INCHES		MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.068	0.078	1.73	1.99	
A1	0.002	0.008	0.05	0.21	
В	0.010	0.015	0.25	0.38	
С	0.004	0.008	0.09	0.20	
D	SI	EE VARI	ATIONS		
Е	0.205	0.212	5.20	5.38	
е	0.0256 BSC		0.65	BSC	
Ι	0.301	0.311	7.65	7.90	
┙	0.025	0.037	0.63	0.95	
α	0 8		0	8	

		INCHES		MILLIM	ETERS	
		MIN	MAX	MIN	MAX	N
	D	0.239	0.249	6.07	6.33	14L
	D	0.239	0.249	6.07	6.33	16L
	D	0.278	0.289	7.07	7.33	20L
	D	0.317	0.328	8.07	8.33	24L
	D	0.397	0.407	10.07	10.33	28L

SSOP





NOTES:

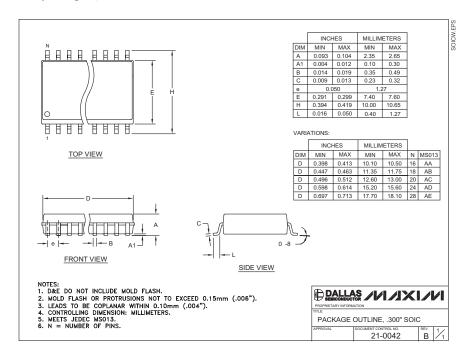
- 1. D&E DO NOT INCLUDE MOLD FLASH.
- 2. MOLD FLASH OR PROTRUSIONS NOT TO EXCEED .15 MM (.006").
- 3. CONTROLLING DIMENSION: MILLIMETERS.
- 4. MEETS JEDEC MO150.
- 5. LEADS TO BE COPLANAR WITHIN 0.10 MM.

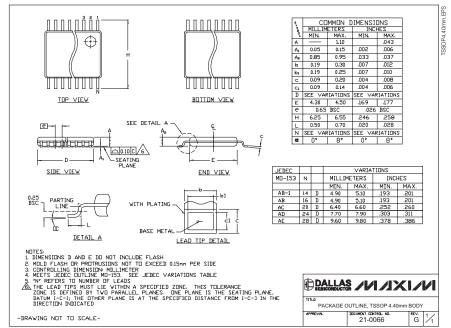


M/IXI/N/

Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to www.maxim-ic.com/packages.)





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